

64Mb (x32) SDRAM PART NUMBER

PART NUMBER	ARCHITECTURE
MT48LC2M32B2TG	2 Meg x 32

GENERAL DESCRIPTION

The 64Mb SDRAM is a high-speed CMOS, dynamic random-access memory containing 67,108,864-bits. It is internally configured as a quad-bank DRAM with a synchronous interface (all signals are registered on the positive edge of the clock signal, CLK). Each of the 16,777,216-bit banks is organized as 2,048 rows by 256 columns by 32 bits.

Read and write accesses to the SDRAM are burst oriented; accesses start at a selected location and continue for a programmed number of locations in a programmed sequence. Accesses begin with the registration of an ACTIVE command, which is then followed by a READ or WRITE command. The address bits registered coincident with the ACTIVE command are used to select the bank and row to be accessed (BA0, BA1 select the bank, A0-A10 select the row). The address bits registered coincident with the READ or WRITE command are used to select the starting column location for the burst access.

The SDRAM provides for programmable READ or WRITE burst lengths of 1, 2, 4, or 8 locations, or the full page, with a burst terminate option. An auto precharge function may be enabled to provide a self-timed row precharge that is initiated at the end of the burst sequence.

The 64Mb SDRAM uses an internal pipelined architecture to achieve high-speed operation. This architecture is compatible with the $2n$ rule of prefetch architectures, but it also allows the column address to be changed on every clock cycle to achieve a high-speed, fully random access. Precharging one bank while accessing one of the other three banks will hide the precharge cycles and provide seamless, high-speed, random-access operation.

The 64Mb SDRAM is designed to operate in 3.3V, low-power memory systems. An auto refresh mode is provided, along with a power-saving, power-down mode. All inputs and outputs are LVTTL-compatible.

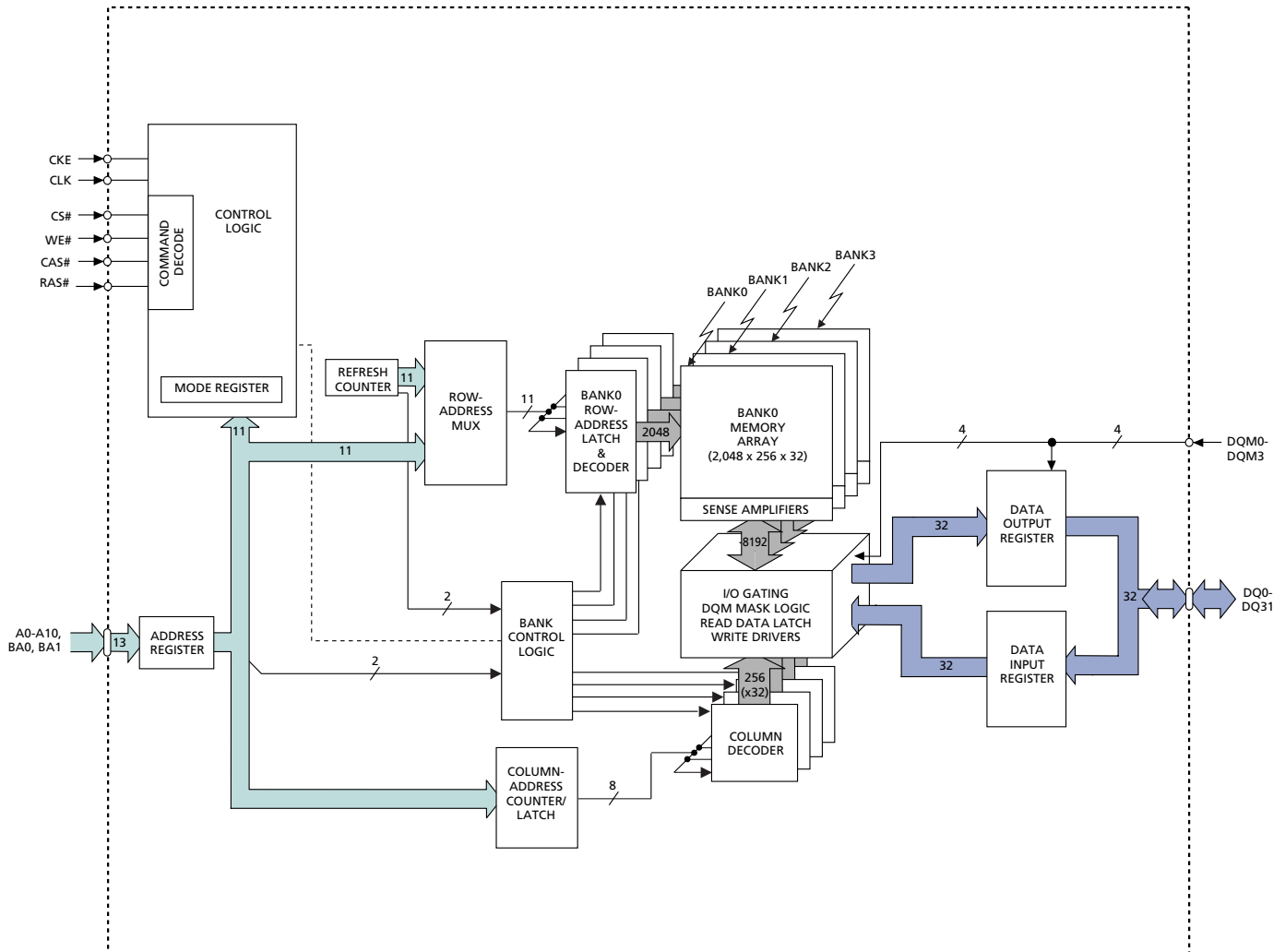
SDRAMs offer substantial advances in DRAM operating performance, including the ability to synchronously burst data at a high data rate with automatic column-address generation, the ability to interleave between internal banks to hide precharge time and the capability to randomly change column addresses on each clock cycle during a burst access.

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FUNCTIONAL BLOCK DIAGRAM

2 Meg x 32 SDRAM



PIN DESCRIPTIONS

PIN NUMBERS	SYMBOL	TYPE	DESCRIPTION
68	CLK	Input	Clock: CLK is driven by the system clock. All SDRAM input signals are sampled on the positive edge of CLK. CLK also increments the internal burst counter and controls the output registers.
67	CKE	Input	Clock Enable: CKE activates (HIGH) and deactivates (LOW) the CLK signal. Deactivating the clock provides PRECHARGE POWER-DOWN and SELF REFRESH operation (all banks idle), ACTIVE POWER-DOWN (row active in any bank) or CLOCK SUSPEND operation (burst/access in progress). CKE is synchronous except after the device enters power-down and self refresh modes, where CKE becomes asynchronous until after exiting the same mode. The input buffers, including CLK, are disabled during power-down and self refresh modes, providing low standby power. CKE may be tied HIGH.
20	CS#	Input	Chip Select: CS# enables (registered LOW) and disables (registered HIGH) the command decoder. All commands are masked when CS# is registered HIGH. CS# provides for external bank selection on systems with multiple banks. CS# is considered part of the command code.
17, 18, 19	WE#, CAS#, RAS#	Input	Command Inputs: WE#, CAS#, and RAS# (along with CS#) define the command being entered.
16, 71, 28, 59	DQM0-DQM3	Input	Input/Output Mask: DQM is sampled HIGH and is an input mask signal for write accesses and an output enable signal for read accesses. Input data is masked during a WRITE cycle. The output buffers are placed in a High-Z state (two-clock latency) during a READ cycle. DQM0 corresponds to DQ0-DQ7; DQM1 corresponds to DQ8-DQ15; DQM2 corresponds to DQ16-DQ23; and DQM3 corresponds to DQ24-DQ31. DQM0-DQM3 are considered same state when referenced as DQM.
22, 23	BA0, BA1	Input	Bank Address Input(s): BA0 and BA1 define to which bank the ACTIVE, READ, WRITE or PRECHARGE command is being applied.
25-27, 60-66, 24	A0-A10	Input	Address Inputs: A0-A10 are sampled during the ACTIVE command (row-address A0-A10) and READ/WRITE command (column-address A0-A7 with A10 defining auto precharge) to select one location out of the memory array in the respective bank. A10 is sampled during a PRECHARGE command to determine if all banks are to be precharged (A10 HIGH) or bank selected by BA0, BA1 (LOW). The address inputs also provide the op-code during a LOAD MODE REGISTER command.
2, 4, 5, 7, 8, 10, 11, 13, 74, 76, 77, 79, 80, 82, 83, 85, 31, 33, 34, 36, 37, 39, 40, 42, 45, 47, 48, 50, 51, 53, 54, 56	DQ0-DQ31	Input/Output	Data I/Os: Data bus.
14, 21, 30, 57, 69, 70, 73	NC	–	No Connect: These pins should be left unconnected. Pin 70 is reserved for SSTL reference voltage supply.
3, 9, 35, 41, 49, 55, 75, 81	V _{DDQ}	Supply	DQ Power Supply: Isolated on the die for improved noise immunity.
6, 12, 32, 38, 46, 52, 78, 84	V _{SSQ}	Supply	DQ Ground: Provide isolated ground to DQs for improved noise immunity.
1, 15, 29, 43	V _{DD}	Supply	Power Supply: +3.3V ±0.3V. (See note 27 on page 35.)
44, 58, 72, 86	V _{SS}	Supply	Ground.

Commands

Truth Table 1 provides a quick reference of available commands. This is followed by a written description of each command. Three additional Truth Tables

appear following the Operation section; these tables provide current state/next state information.

TRUTH TABLE 1 – COMMANDS AND DQM OPERATION

(Note: 1)

NAME (FUNCTION)	CS#	RAS#	CAS#	WE#	DQM	ADDR	DQs	NOTES
COMMAND INHIBIT (NOP)	H	X	X	X	X	X	X	
NO OPERATION (NOP)	L	H	H	H	X	X	X	
ACTIVE (Select bank and activate row)	L	L	H	H	X	Bank/Row	X	3
READ (Select bank and column, and start READ burst)	L	H	L	H	L/H ⁸	Bank/Col	X	4
WRITE (Select bank and column, and start WRITE burst)	L	H	L	L	L/H ⁸	Bank/Col	Valid	4
BURST TERMINATE	L	H	H	L	X	X	Active	
PRECHARGE (Deactivate row in bank or banks)	L	L	H	L	X	Code	X	5
AUTO REFRESH or SELF REFRESH (Enter self refresh mode)	L	L	L	H	X	X	X	6, 7
LOAD MODE REGISTER	L	L	L	L	X	Op-Code	X	2
Write Enable/Output Enable	–	–	–	–	L	–	Active	8
Write Inhibit/Output High-Z	–	–	–	–	H	–	High-Z	8

- NOTE:**
1. CKE is HIGH for all commands shown except SELF REFRESH.
 2. A0-A10 define the op-code written to the Mode Register.
 3. A0-A10 provide row address, BA0 and BA1 determine which bank is made active.
 4. A0-A7 provide column address; A10 HIGH enables the auto precharge feature (nonpersistent), while A10 LOW disables the auto precharge feature; BA0 and BA1 determine which bank is being read from or written to.
 5. A10 LOW: BA0 and BA1 determine the bank being precharged. A10 HIGH: All banks precharged and BA0 and BA1 are "Don't Care."
 6. This command is AUTO REFRESH if CKE is HIGH; SELF REFRESH if CKE is LOW.
 7. Internal refresh counter controls row addressing; all inputs and I/Os are "Don't Care" except for CKE.
 8. Activates or deactivates the DQs during WRITES (zero-clock delay) and READs (two-clock delay). DQM0 controls DQ0-DQ7; DQM1 controls DQ8-DQ15; DQM2 controls DQ16-DQ23; and DQM3 controls DQ24-DQ31.

BURST TERMINATE

The BURST TERMINATE command is used to truncate either fixed-length or full-page bursts. The most recently registered READ or WRITE command prior to the BURST TERMINATE command will be truncated, as shown in the Operation section of this data sheet.

AUTO REFRESH

AUTO REFRESH is used during normal operation of the SDRAM and is analogous to CAS#-BEFORE-RAS# (CBR) REFRESH in conventional DRAMs. This command is nonpersistent, so it must be issued each time a refresh is required.

The addressing is generated by the internal refresh controller. This makes the address bits “Don’t Care” during an AUTO REFRESH command. The 64Mb SDRAM requires 4,096 AUTO REFRESH cycles every 64ms (t_{REF}), regardless of width option. Providing a distributed AUTO REFRESH command every 15.625 μ s will meet the refresh requirement and ensure that each row is refreshed. Alternatively, 4,096 AUTO REFRESH commands can be issued in a burst at the minimum cycle rate (t_{RC}), once every 64ms.

SELF REFRESH

The SELF REFRESH command can be used to retain data in the SDRAM, even if the rest of the system is powered down. When in the self refresh mode, the SDRAM retains data without external clocking. The SELF REFRESH command is initiated like an AUTO REFRESH command except CKE is disabled (LOW). Once the SELF REFRESH command is registered, all the inputs to the SDRAM become “Don’t Care” with the exception of CKE, which must remain LOW.

Once self refresh mode is engaged, the SDRAM provides its own internal clocking, causing it to perform its own AUTO REFRESH cycles. The SDRAM must remain in self refresh mode for a minimum period equal to t_{RAS} and may remain in self refresh mode for an indefinite period beyond that.

The procedure for exiting self refresh requires a sequence of commands. First, CLK must be stable (stable clock is defined as a signal cycling within timing constraints specified for the clock pin) prior to CKE going back HIGH. Once CKE is HIGH, the SDRAM must have NOP commands issued (a minimum of two clocks) for t_{XSR} because time is required for the completion of any internal refresh in progress.

Upon exiting SELF REFRESH mode, AUTO REFRESH commands must be issued every 15.625ms or less as both SELF REFRESH and AUTO REFRESH utilize the row refresh counter.

Operation

BANK/ROW ACTIVATION

Before any READ or WRITE commands can be issued to a bank within the SDRAM, a row in that bank must be “opened.” This is accomplished via the ACTIVE command, which selects both the bank and the row to be activated. See Figure 3.

After opening a row (issuing an ACTIVE command), a READ or WRITE command may be issued to that row, subject to the t_{RCD} specification. t_{RCD} (MIN) should be divided by the clock period and rounded up to the next whole number to determine the earliest clock edge after the ACTIVE command on which a READ or WRITE command can be issued. For example, a t_{RCD} specification of 20ns with a 125 MHz clock (8ns period) results in 2.5 clocks, rounded to 3. This is reflected in Figure 4, which covers any case where $2 < t_{RCD} \text{ (MIN)} / t_{CK} - 3$. (The same procedure is used to convert other specification limits from time units to clock cycles.)

A subsequent ACTIVE command to a different row in the same bank can only be issued after the previous active row has been “closed” (precharged). The minimum time interval between successive ACTIVE commands to the same bank is defined by t_{RC} .

A subsequent ACTIVE command to another bank can be issued while the first bank is being accessed, which results in a reduction of total row-access overhead. The minimum time interval between successive ACTIVE commands to different banks is defined by t_{RRD} .

Figure 3
Activating a Specific Row in a Specific Bank

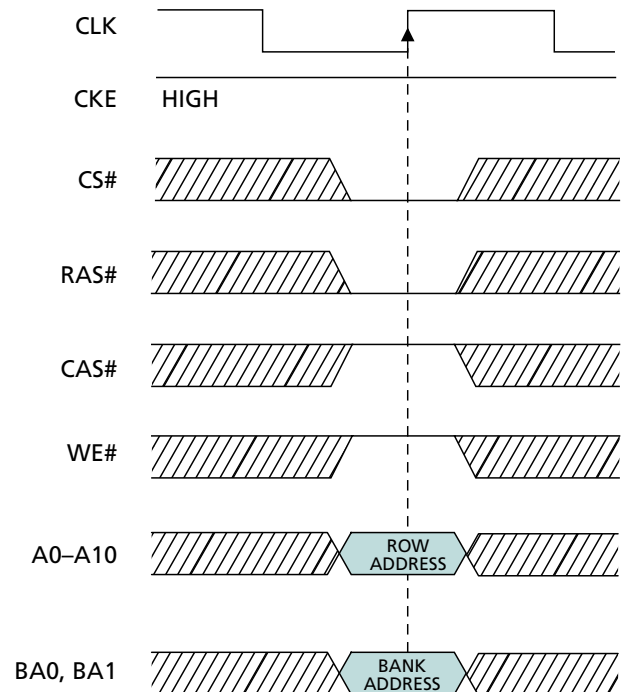
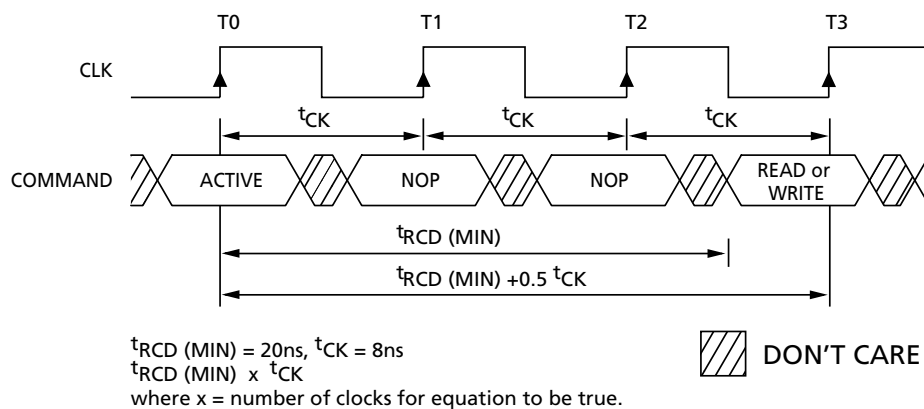


Figure 4
Example: Meeting $t_{RCD} \text{ (MIN)}$ When $2 < t_{RCD} \text{ (MIN)} / t_{CK} - 3$



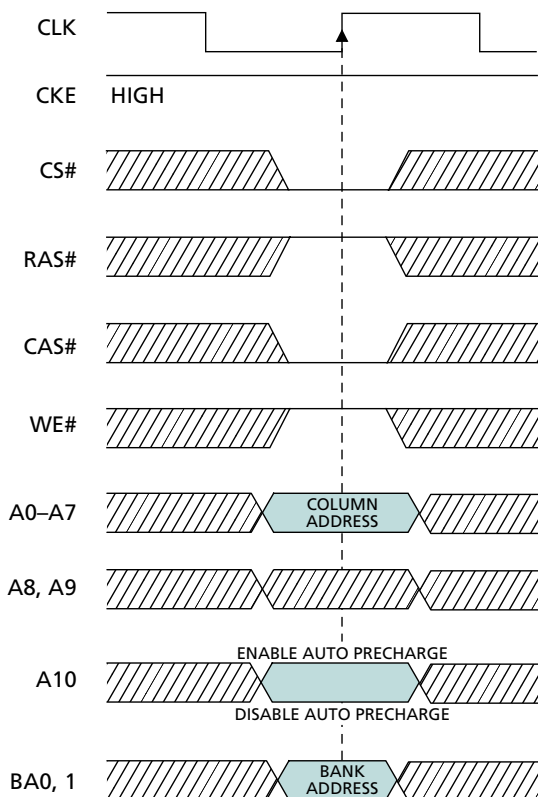
READS

READ bursts are initiated with a READ command, as shown in Figure 5.

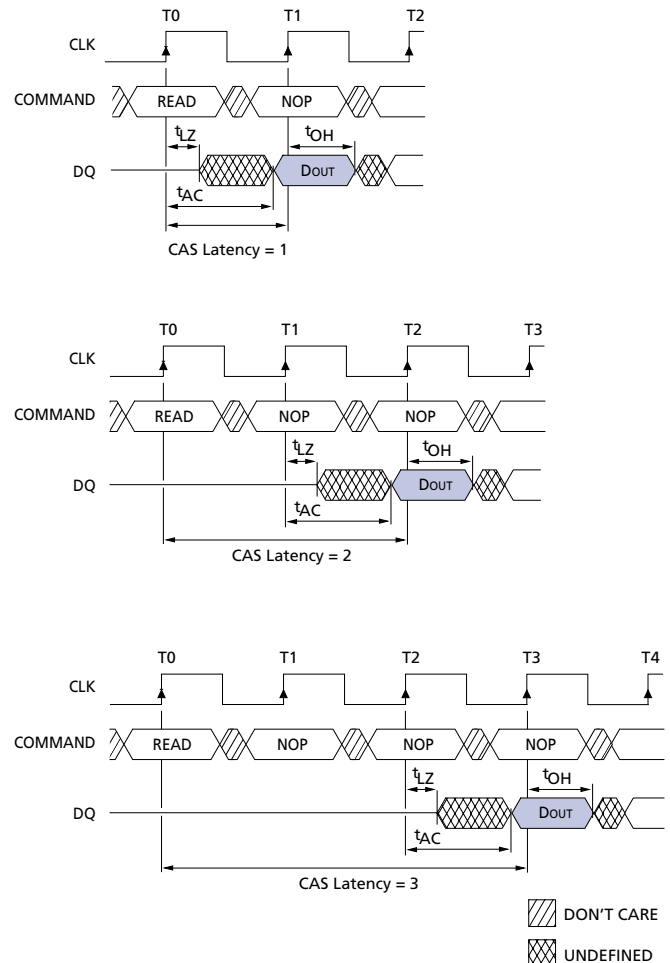
The starting column and bank addresses are provided with the READ command, and auto precharge is either enabled or disabled for that burst access. If auto precharge is enabled, the row being accessed is precharged at the completion of the burst. For the generic READ commands used in the following illustrations, auto precharge is disabled.

During READ bursts, the valid data-out element from the starting column address will be available following the CAS latency after the READ command. Each subsequent data-out element will be valid by the next positive clock edge. Figure 6 shows general timing for each possible CAS latency setting.

**Figure 5
READ Command**



**Figure 6
CAS Latency**



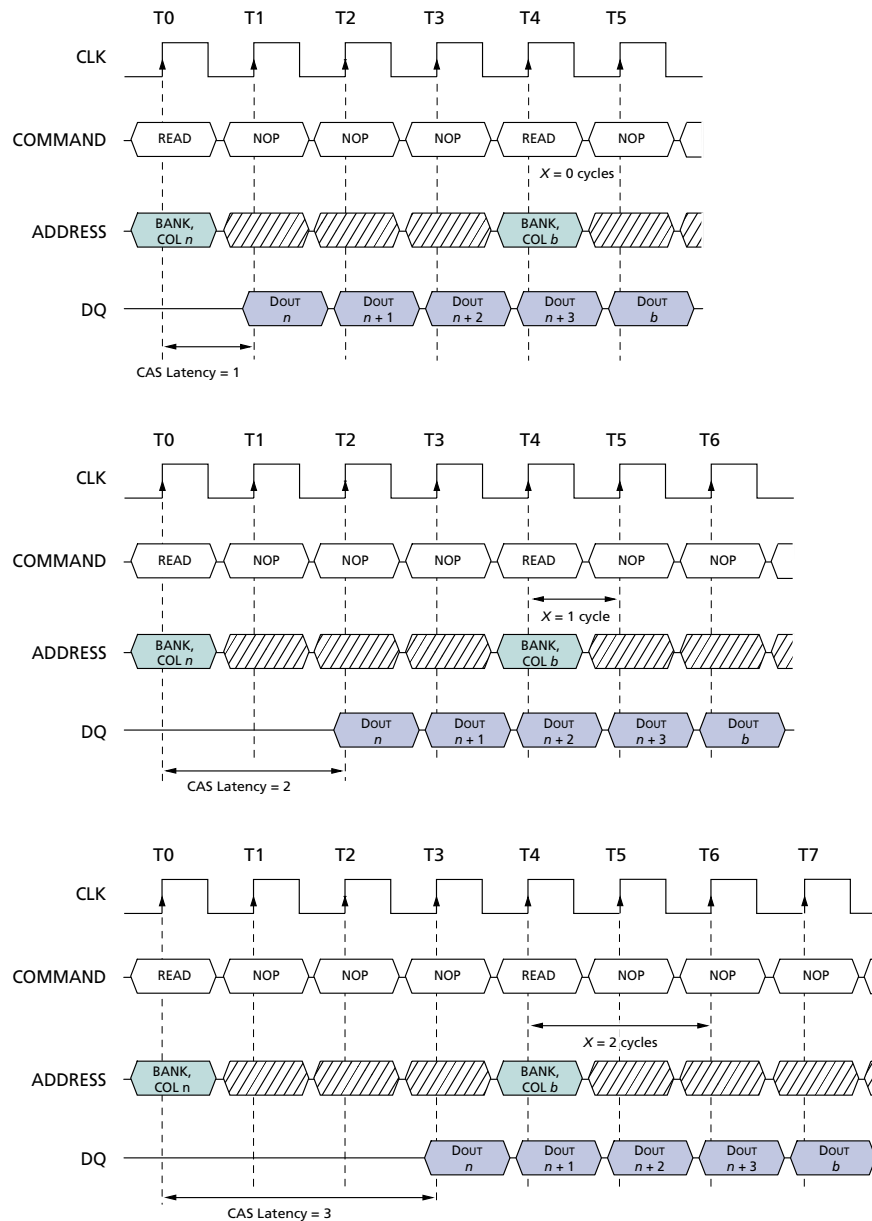
Upon completion of a burst, assuming no other commands have been initiated, the DQs will go High-Z. A full-page burst will continue until terminated. (At the end of the page, it will wrap to column 0 and continue.)

Data from any READ burst may be truncated with a subsequent READ command, and data from a fixed-length READ burst may be immediately followed by data from a READ command. In either case, a continuous flow of data can be maintained. The first data element from the new burst follows either the last element of a completed burst or the last desired data element of a longer burst that is being truncated. The new READ command should be issued x cycles before the clock edge at which the last desired data element is valid, where x equals the CAS latency minus one. This is shown in Figure 7 for CAS latencies of one, two and

three; data element $n + 3$ is either the last of a burst of four or the last desired of a longer burst. This 64Mb SDRAM uses a pipelined architecture and therefore does not require the $2n$ rule associated with a prefetch architecture. A READ command can be initiated on any

clock cycle following a previous READ command. Full-speed random read accesses can be performed to the same bank, as shown in Figure 8, or each subsequent READ may be performed to a different bank.

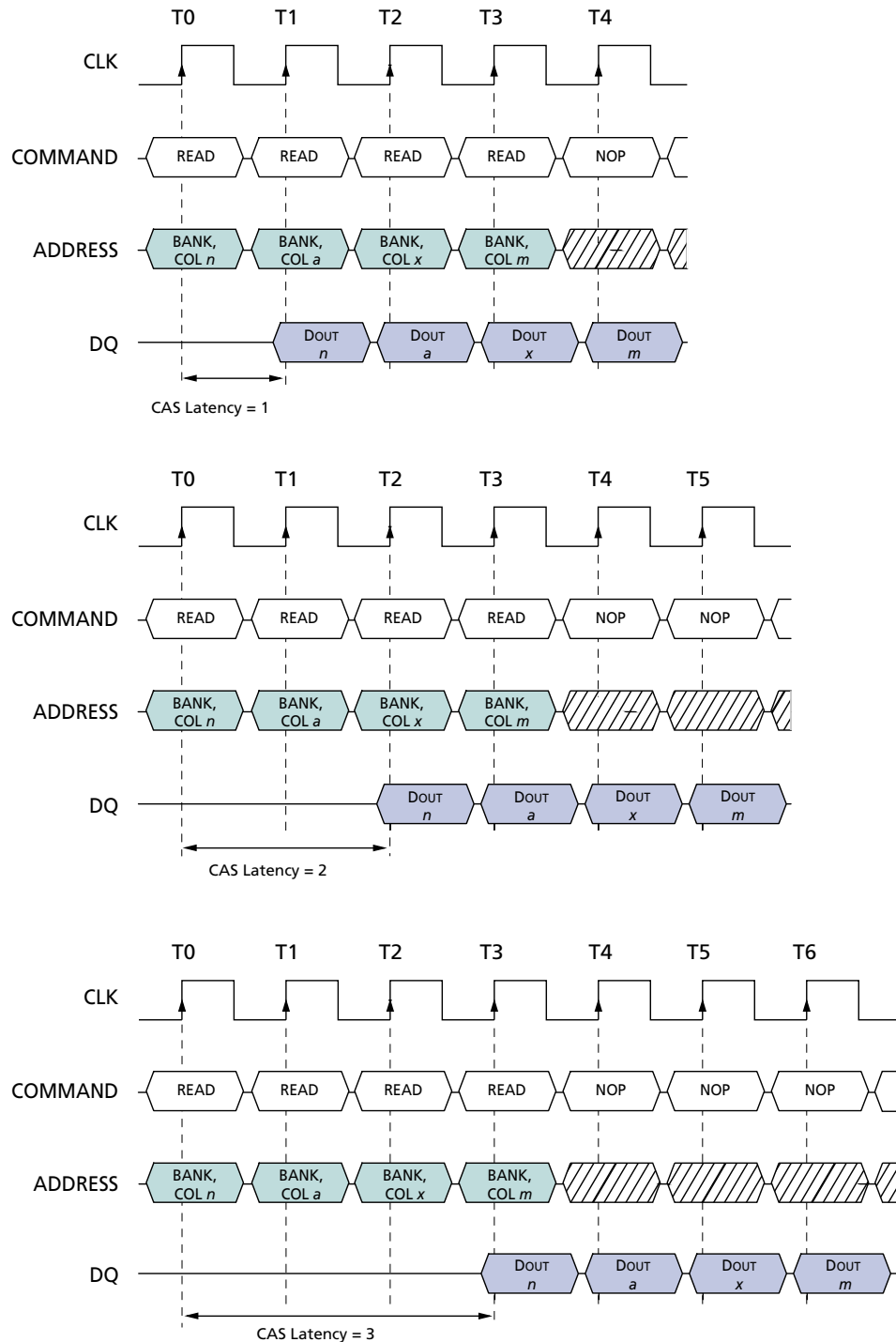
Figure 7
Consecutive READ Bursts



NOTE: Each READ command may be to either bank. DQM is LOW.

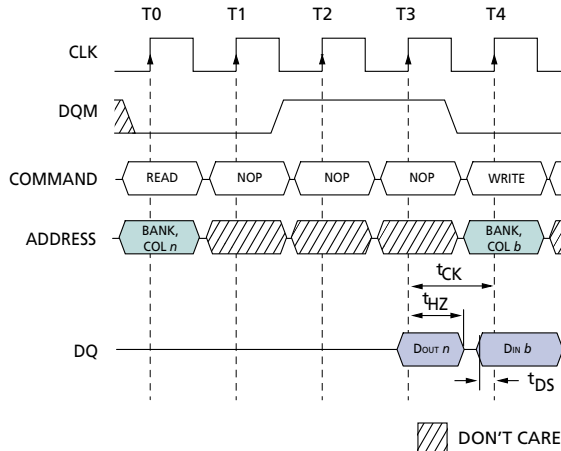
DON'T CARE

Figure 8
Random READ Accesses



Data from any READ burst may be truncated with a subsequent WRITE command, and data from a fixed-length READ burst may be immediately followed by data from a WRITE command (subject to bus turn-around limitations). The WRITE burst may be initiated on the clock edge immediately following the last (or last desired) data element from the READ burst, provided that I/O contention can be avoided. In a given system design, there may be a possibility that the device driving the input data will go Low-Z before the SDRAM DQs go High-Z. In this case, at least a single-cycle delay should occur between the last read data and the WRITE command.

**Figure 9
READ to WRITE**

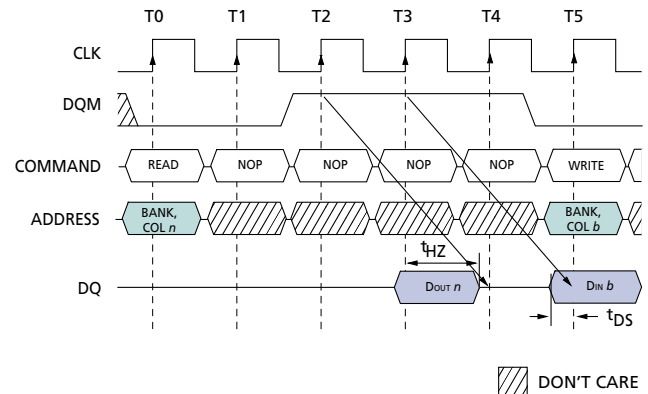


NOTE: A CAS latency of three is used for illustration. The READ command may be to any bank, and the WRITE command

The DQM input is used to avoid I/O contention, as shown in Figures 9 and 10. The DQM signal must be asserted (HIGH) at least two clocks prior to the WRITE command (DQM latency is two clocks for output buffers) to suppress data-out from the READ. Once the WRITE command is registered, the DQs will go High-Z (or remain High-Z), regardless of the state of the DQM signal; provided the DQM was active on the clock just prior to the WRITE command that truncated the READ command. If not, the second WRITE will be an invalid WRITE. For example, if DQM was low during T4 in Figure 10, then the WRITES at T5 and T7 would be valid, while the WRITE at T6 would be invalid.

The DQM signal must be de-asserted prior to the WRITE command (DQM latency is zero clocks for input buffers) to ensure that the written data is not masked. Figure 9 shows the case where the clock frequency allows for bus contention to be avoided without adding a NOP cycle, and Figure 10 shows the case where the additional NOP is needed.

**Figure 10
READ to WRITE with
Extra Clock Cycle**



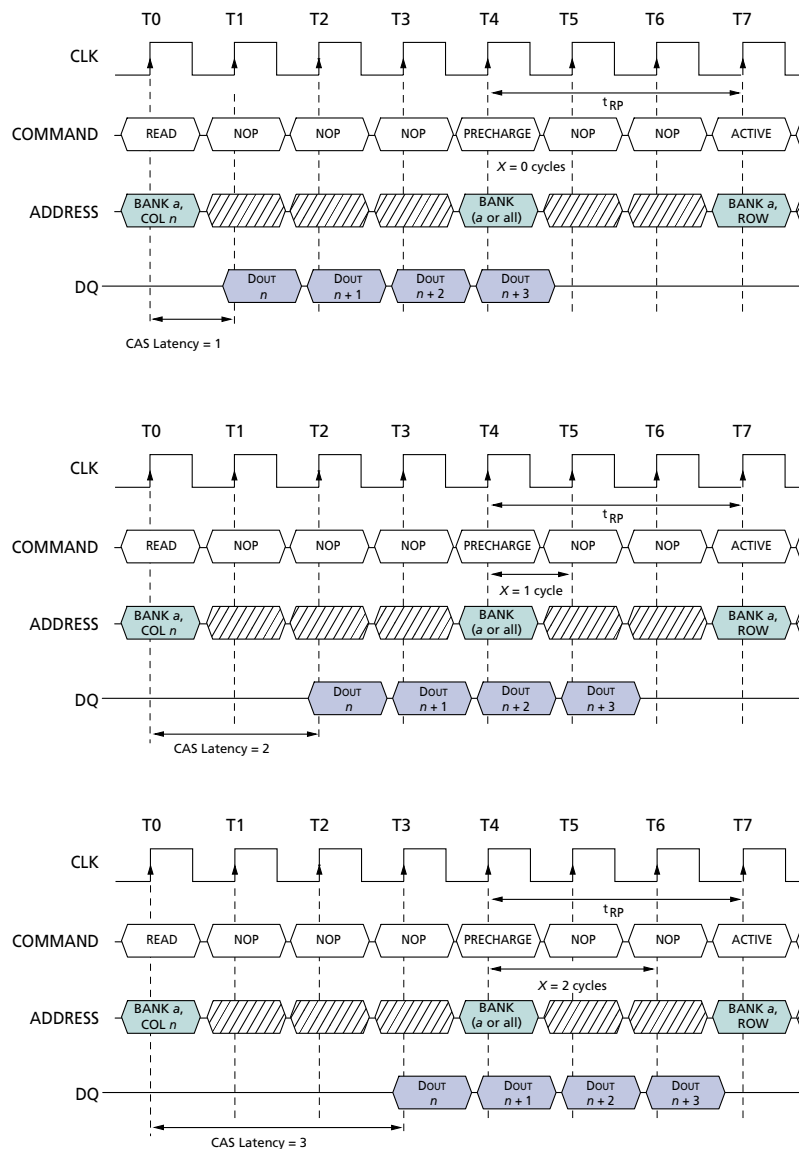
NOTE: A CAS latency of three is used for illustration. The READ command may be to any bank, and the WRITE command may be to any bank.

A fixed-length READ burst may be followed by, or truncated with, a PRECHARGE command to the same bank (provided that auto precharge was not activated), and a full-page burst may be truncated with a PRECHARGE command to the same bank. The PRECHARGE command should be issued x cycles before the clock edge at which the last desired data element is valid, where x equals the CAS latency minus one. This is shown in Figure 11 for each possible CAS

latency; data element $n + 3$ is either the last of a burst of four or the last desired of a longer burst. Following the PRECHARGE command, a subsequent command to the same bank cannot be issued until t_{RP} is met. Note that part of the row precharge time is hidden during the access of the last data element(s).

In the case of a fixed-length burst being executed to completion, a PRECHARGE command issued at the optimum time (as described above) provides the same

**Figure 11
READ to PRECHARGE**



NOTE: DQM is LOW.

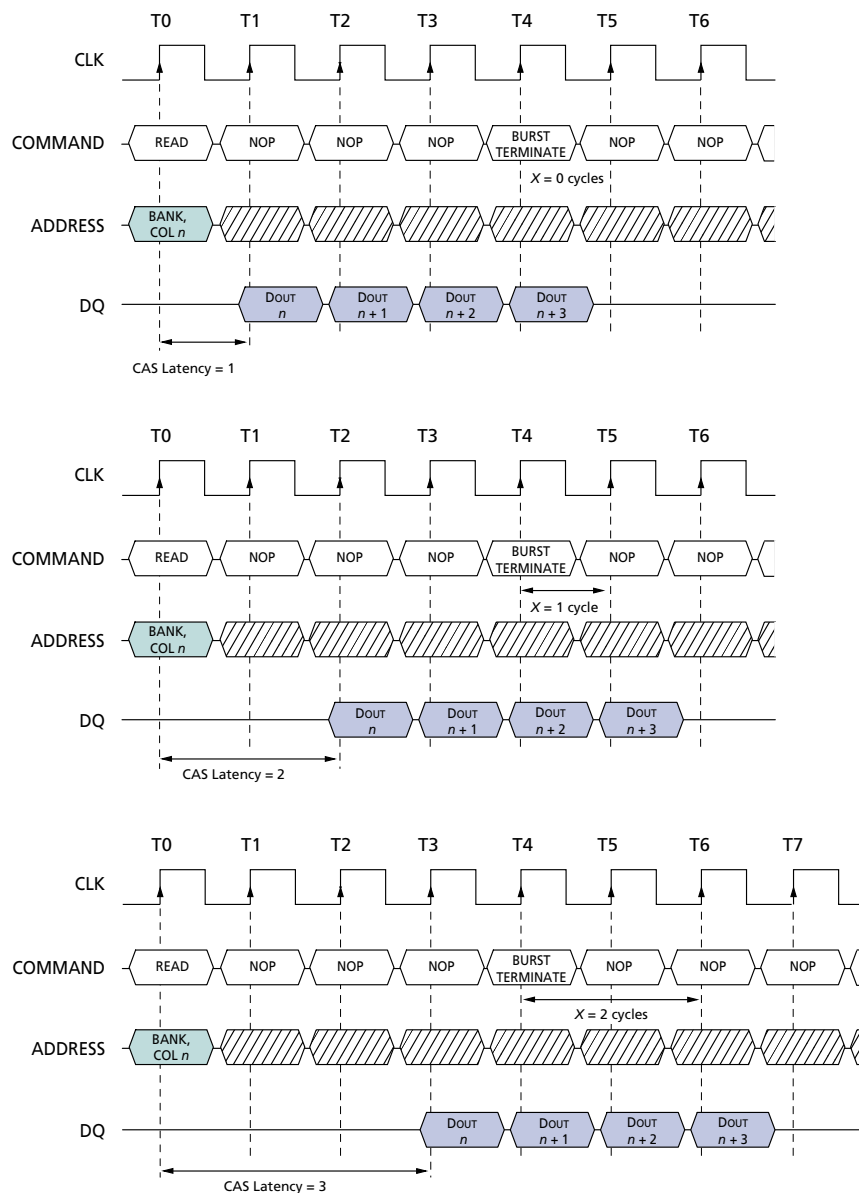
DON'T CARE

operation that would result from the same fixed-length burst with auto precharge. The disadvantage of the PRECHARGE command is that it requires that the command and address buses be available at the appropriate time to issue the command; the advantage of the PRECHARGE command is that it can be used to truncate fixed-length or full-page bursts.

Full-page READ bursts can be truncated with the BURST TERMINATE command, and fixed-length READ

bursts may be truncated with a BURST TERMINATE command, provided that auto precharge was not activated. The BURST TERMINATE command should be issued x cycles before the clock edge at which the last desired data element is valid, where x equals the CAS latency minus one. This is shown in Figure 12 for each possible CAS latency; data element $n + 3$ is the last desired data element of a longer burst.

**Figure 12
Terminating a READ Burst**



NOTE: DQM is LOW.

DON'T CARE

WRITES

WRITE bursts are initiated with a WRITE command, as shown in Figure 13.

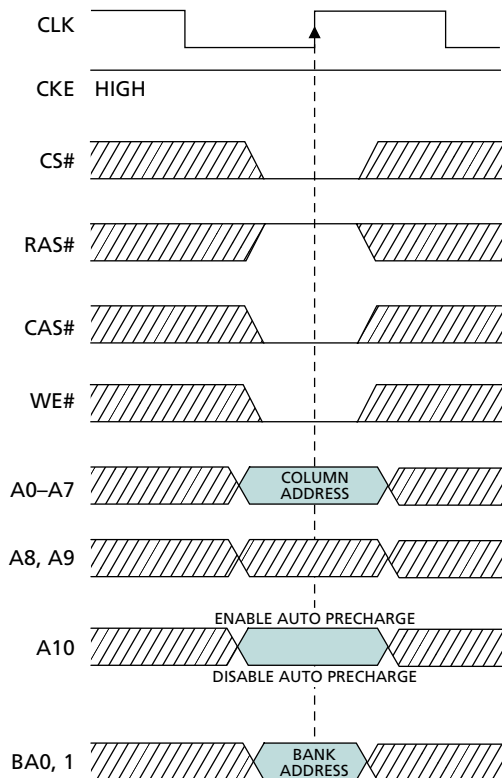
The starting column and bank addresses are provided with the WRITE command, and auto precharge is either enabled or disabled for that access. If auto precharge is enabled, the row being accessed is precharged at the completion of the burst. For the generic WRITE commands used in the following illustrations, auto precharge is disabled.

During WRITE bursts, the first valid data-in element will be registered coincident with the WRITE command. Subsequent data elements will be registered on each successive positive clock edge. Upon completion of a fixed-length burst, assuming no other commands have been initiated, the DQs will remain High-Z and any additional input data will be ignored (see Figure 14). A full-page burst will continue until terminated. (At the end of the page, it will wrap to column 0 and continue.)

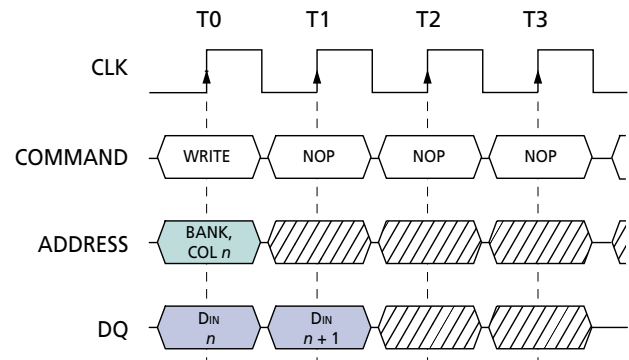
Data for any WRITE burst may be truncated with a subsequent WRITE command, and data for a fixed-length WRITE burst may be immediately followed by data for a WRITE command. The new WRITE command

can be issued on any clock following the previous WRITE command, and the data provided coincident with the new command applies to the new command. An example is shown in Figure 15. Data $n + 1$ is either the last of a burst of two or the last desired of a longer burst. This 64Mb SDRAM uses a pipelined architecture and therefore does not require the $2n$ rule associated with a prefetch architecture. A WRITE command can be initiated on any clock cycle following a previous WRITE command. Full-speed random write accesses within a page can be performed to the same bank, as shown in Figure 16, or each subsequent WRITE may be performed to a different bank.

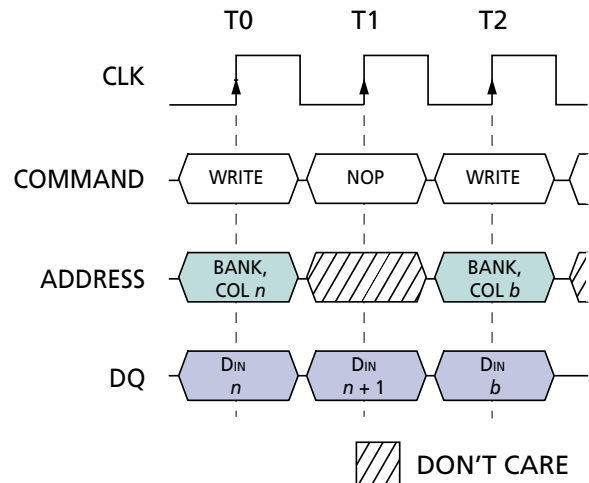
**Figure 13
WRITE Command**



**Figure 14
WRITE Burst**



**Figure 15
WRITE to WRITE**



NOTE: DQM is LOW. Each WRITE command may be to any bank.

CLOCK SUSPEND

The clock suspend mode occurs when a column access/burst is in progress and CKE is registered LOW. In the clock suspend mode, the internal clock is deactivated, “freezing” the synchronous logic.

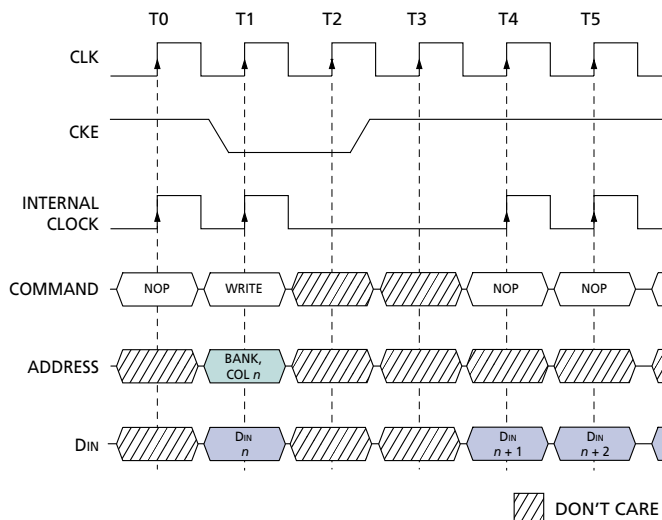
For each positive clock edge on which CKE is sampled LOW, the next internal positive clock edge is suspended. Any command or data present on the input pins at the time of a suspended internal clock edge is ignored; any data present on the DQ pins remains driven; and burst counters are not incremented, as long as the clock is suspended. (See examples in Figures 22 and 23.)

Clock suspend mode is exited by registering CKE HIGH; the internal clock and related operation will resume on the subsequent positive clock edge.

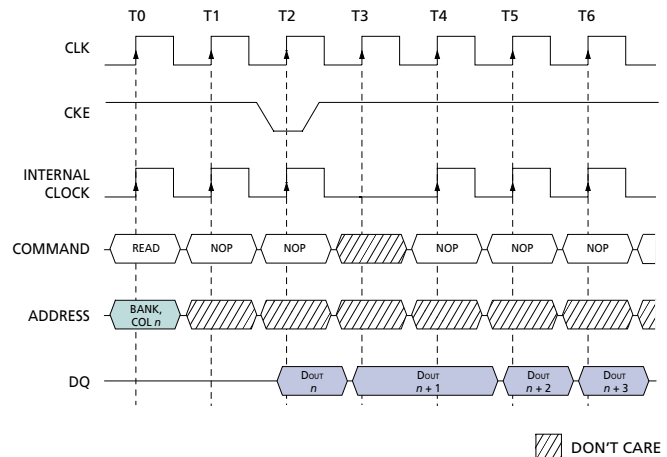
BURST READ/SINGLE WRITE

The burst read/single write mode is entered by programming the write burst mode bit (M9) in the Mode Register to a logic 1. In this mode, all WRITE commands result in the access of a single column location (burst of one), regardless of the programmed burst length. READ commands access columns according to the programmed burst length and sequence, just as in the normal mode of operation (M9 = 0).

**Figure 22
CLOCK SUSPEND During WRITE Burst**



**Figure 23
CLOCK SUSPEND During READ Burst**



NOTE: For this example, CAS latency = 2, burst length = 4 or greater, and DQM is LOW.

CONCURRENT AUTO PRECHARGE

An access command to (READ or WRITE) another bank while an access command with auto precharge enabled is executing is not allowed by SDRAMs, unless the SDRAM supports CONCURRENT AUTO PRECHARGE. Micron SDRAMs support CONCURRENT AUTO PRECHARGE. Four cases where CONCURRENT AUTO PRECHARGE occurs are defined below.

READ with auto precharge

1. Interrupted by a READ (with or without auto precharge): A READ to bank *m* will interrupt a READ

on bank *n*, CAS latency later. The PRECHARGE to bank *n* will begin when the READ to bank *m* is registered (Figure 24).

2. Interrupted by a WRITE (with or without auto precharge): A WRITE to bank *m* will interrupt a READ on bank *n* when registered. DQM should be used two clocks prior to the WRITE command to prevent bus contention. The PRECHARGE to bank *n* will begin when the WRITE to bank *m* is registered (Figure 25).

Figure 24
READ With Auto Precharge Interrupted by a READ

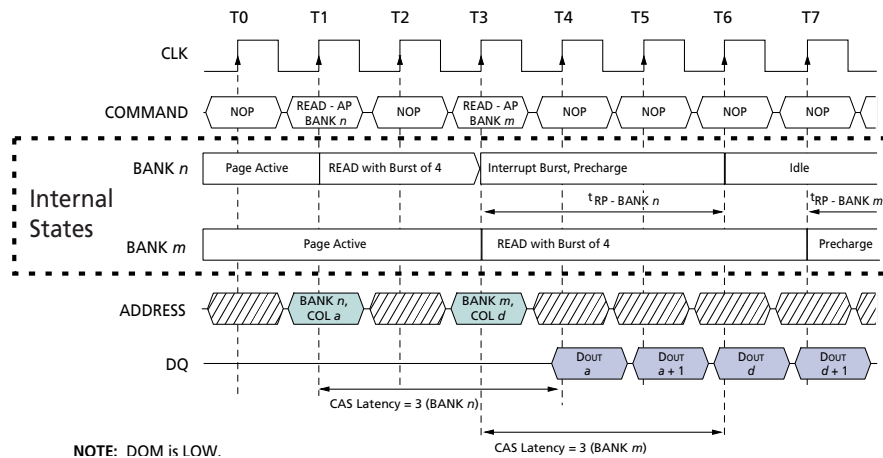
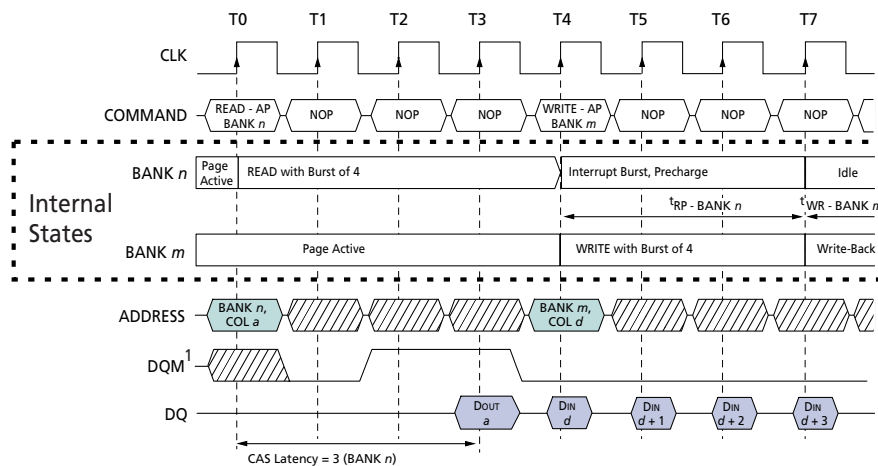


Figure 25
READ With Auto Precharge Interrupted by a WRITE



DON'T CARE

WRITE WITH AUTO PRECHARGE

3. Interrupted by a READ (with or without auto precharge): A READ to bank m will interrupt a WRITE on bank n when registered, with the data-out appearing CAS latency later. The PRECHARGE to bank n will begin after t_{WR} is met, where t_{WR} begins when the READ to bank m is registered. The last valid WRITE to bank n will be data-in registered one clock prior to the READ to bank m (Figure 26).

4. Interrupted by a WRITE (with or without auto precharge): A WRITE to bank m will interrupt a WRITE on bank n when registered. The PRECHARGE to bank n will begin after t_{WR} is met, where t_{WR} begins when the WRITE to bank m is registered. The last valid data WRITE to bank n will be data registered one clock prior to a WRITE to bank m (Figure 27).

Figure 26
WRITE With Auto Precharge Interrupted by a READ

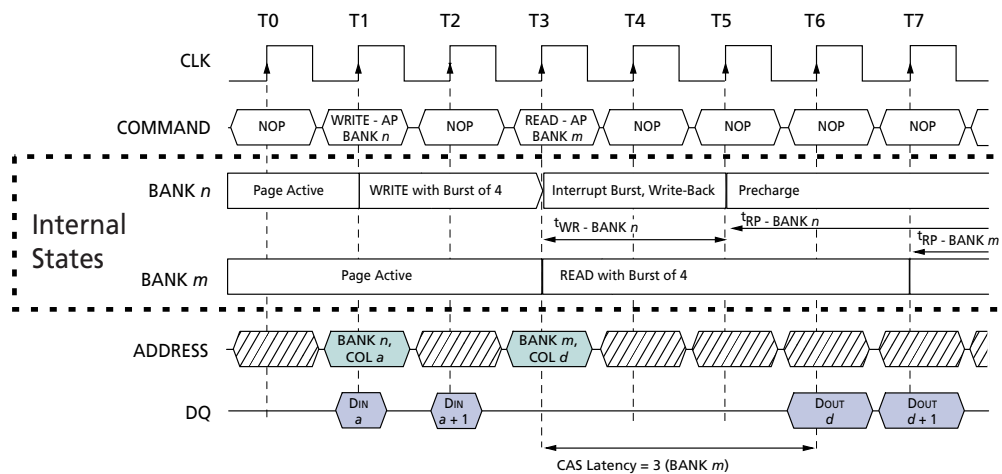
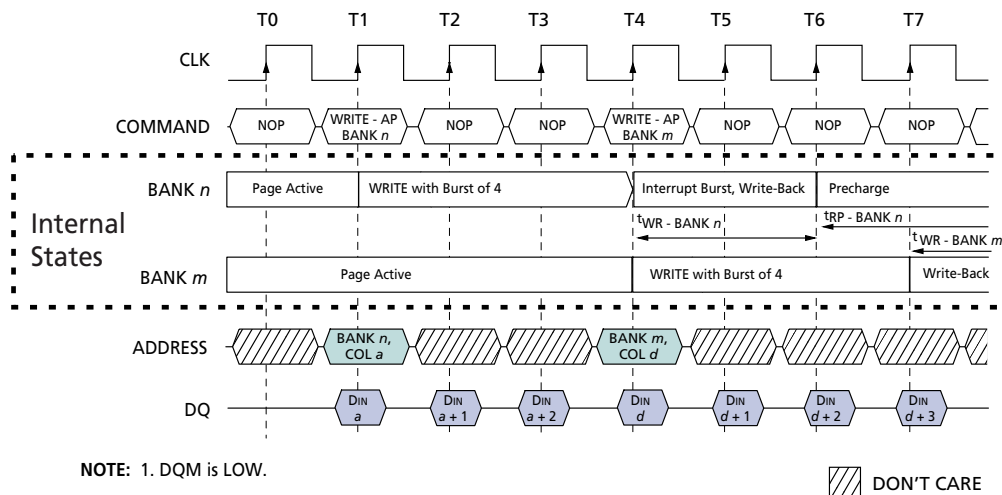


Figure 27
WRITE With Auto Precharge Interrupted by a WRITE



TRUTH TABLE 2 – CKE

(Notes: 1-4)

CKE _{n-1}	CKE _n	CURRENT STATE	COMMAND _n	ACTION _n	NOTES
L	L	Power-Down	X	Maintain Power-Down	
		Self Refresh	X	Maintain Self Refresh	
		Clock Suspend	X	Maintain Clock Suspend	
L	H	Power-Down	COMMAND INHIBIT or NOP	Exit Power-Down	5
		Self Refresh	COMMAND INHIBIT or NOP	Exit Self Refresh	6
		Clock Suspend	X	Exit Clock Suspend	7
H	L	All Banks Idle	COMMAND INHIBIT or NOP	Power-Down Entry	
		All Banks Idle	AUTO REFRESH	Self Refresh Entry	
		Reading or Writing	VALID	Clock Suspend Entry	
H	H		See Truth Table 3		

- NOTE:**
1. CKE_n is the logic state of CKE at clock edge *n*; CKE_{n-1} was the state of CKE at the previous clock edge.
 2. Current state is the state of the SDRAM immediately prior to clock edge *n*.
 3. COMMAND_n is the command registered at clock edge *n*, and ACTION_n is a result of COMMAND_n.
 4. All states and sequences not shown are illegal or reserved.
 5. Exiting power-down at clock edge *n* will put the device in the all banks idle state in time for clock edge *n* + 1 (provided that ^tCKS is met).
 6. Exiting self refresh at clock edge *n* will put the device in the all banks idle state once ^tXSR is met. COMMAND INHIBIT or NOP commands should be issued on any clock edges occurring during the ^tXSR period. A minimum of two NOP commands must be provided during ^tXSR period.
 7. After exiting clock suspend at clock edge *n*, the device will resume operation and recognize the next command at clock edge *n* + 1.

NOTE (continued):

Write w/Auto

Precharge Enabled: Starts with registration of a WRITE command with auto precharge enabled and ends when t_{RP} has been met. Once t_{RP} is met, the bank will be in the idle state.

5. The following states must not be interrupted by any executable command; COMMAND INHIBIT or NOP commands must be applied on each positive clock edge during these states.

Refreshing: Starts with registration of an AUTO REFRESH command and ends when t_{RC} is met. Once t_{RC} is met, the SDRAM will be in the all banks idle state.

Accessing Mode

Register: Starts with registration of a LOAD MODE REGISTER command and ends when t_{MRD} has been met. Once t_{MRD} is met, the SDRAM will be in the all banks idle state.

Precharging All: Starts with registration of a PRECHARGE ALL command and ends when t_{RP} is met. Once t_{RP} is met, all banks will be in the idle state.

6. All states and sequences not shown are illegal or reserved.
7. Not bank-specific; requires that all banks are idle.
8. May or may not be bank-specific; if all banks are to be precharged, all must be in a valid state for precharging.
9. Not bank-specific; BURST TERMINATE affects the most recent READ or WRITE burst, regardless of bank.
10. READs or WRITEs listed in the Command (Action) column include READs or WRITEs with auto precharge enabled and READs or WRITEs with auto precharge disabled.
11. Does not affect the state of the bank and acts as a NOP to that bank.

NOTE (continued):

4. AUTO REFRESH, SELF REFRESH, and LOAD MODE REGISTER commands may only be issued when all banks are idle.
5. A BURST TERMINATE command cannot be issued to another bank; it applies to the bank represented by the current state only.
6. All states and sequences not shown are illegal or reserved.
7. READs or WRITEs to bank *m* listed in the Command (Action) column include READs or WRITEs with auto precharge enabled and READs or WRITEs with auto precharge disabled.
8. CONCURRENT AUTO PRECHARGE: Bank *n* will initiate the auto precharge command when its burst has been interrupted by bank *m*'s burst.
9. Burst in bank *n* continues as initiated.
10. For a READ without auto precharge interrupted by a READ (with or without auto precharge), the READ to bank *m* will interrupt the READ on bank *n*, CAS latency later (Figure 7).
11. For a READ without auto precharge interrupted by a WRITE (with or without auto precharge), the WRITE to bank *m* will interrupt the READ on bank *n* when registered (Figures 9 and 10). DQM should be used one clock prior to the WRITE command to prevent bus contention.
12. For a WRITE without auto precharge interrupted by a READ (with or without auto precharge), the READ to bank *m* will interrupt the WRITE on bank *n* when registered (Figure 17), with the data-out appearing CAS latency later. The last valid WRITE to bank *n* will be data-in registered one clock prior to the READ to bank *m*.
13. For a WRITE without auto precharge interrupted by a WRITE (with or without auto precharge), the WRITE to bank *m* will interrupt the WRITE on bank *n* when registered (Figure 15). The last valid WRITE to bank *n* will be data-in registered one clock prior to the READ to bank *m*.
14. For a READ with auto precharge interrupted by a READ (with or without auto precharge), the READ to bank *m* will interrupt the READ on bank *n*, CAS latency later. The PRECHARGE to bank *n* will begin when the READ to bank *m* is registered (Figure 24).
15. For a READ with auto precharge interrupted by a WRITE (with or without auto precharge), the WRITE to bank *m* will interrupt the READ on bank *n* when registered. DQM should be used two clocks prior to the WRITE command to prevent bus contention. The PRECHARGE to bank *n* will begin when the WRITE to bank *m* is registered (Figure 25).
16. For a WRITE with auto precharge interrupted by a READ (with or without auto precharge), the READ to bank *m* will interrupt the WRITE on bank *n* when registered, with the data-out appearing CAS latency later. The PRECHARGE to bank *n* will begin after t_{WR} is met, where t_{WR} begins when the READ to bank *m* is registered. The last valid WRITE to bank *n* will be data-in registered one clock prior to the READ to bank *m* (Figure 26).
17. For a WRITE with auto precharge interrupted by a WRITE (with or without auto precharge), the WRITE to bank *m* will interrupt the WRITE on bank *n* when registered. The PRECHARGE to bank *n* will begin after t_{WR} is met, where t_{WR} begins when the WRITE to bank *m* is registered. The last valid WRITE to bank *n* will be data registered one clock prior to the WRITE to bank *m* (Figure 27).

ABSOLUTE MAXIMUM RATINGS*

Voltage on V _{DD} , V _{DDQ} Supply	
Relative to V _{SS}	-1V to +4.6V
Voltage on Inputs, NC or I/O Pins	
Relative to V _{SS}	-1V to +4.6V
Operating Temperature, T _A	0°C to +70°C
Extended Temperature	-40°C to +85°C
Storage Temperature (plastic)	-55°C to +150°C
Power Dissipation	1W

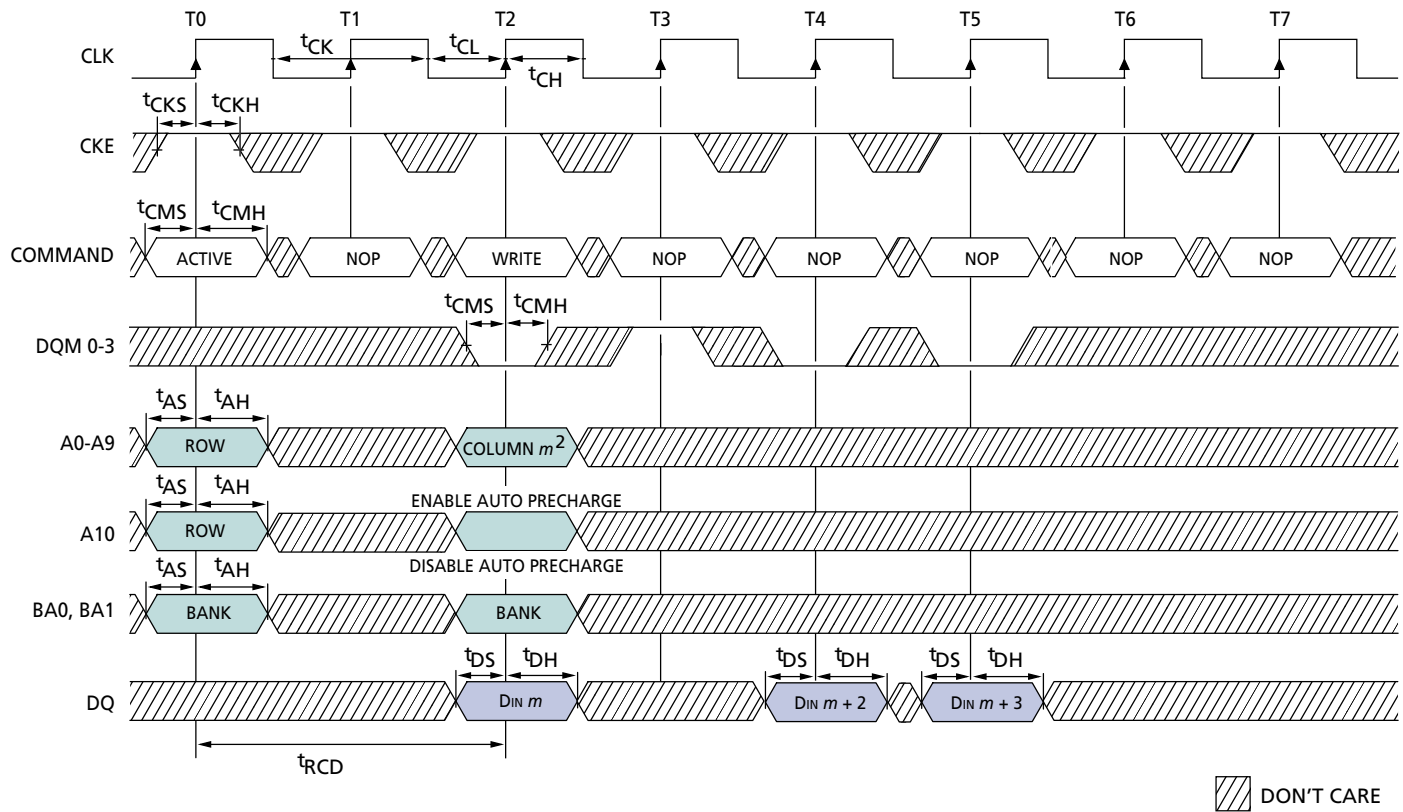
*Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC ELECTRICAL CHARACTERISTICS AND OPERATING CONDITIONS

(Notes: 1, 6, 27; notes appear on page 35) (V_{DD}, V_{DDQ} = +3.3V ±0.3V)

PARAMETER/CONDITION	SYMBOL	MIN	MAX	UNITS	NOTES
SUPPLY VOLTAGE	V _{DD} , V _{DDQ}	3	3.6	V	27
INPUT HIGH VOLTAGE: Logic 1; All inputs	V _{IH}	2	V _{DD} + 0.3	V	22
INPUT LOW VOLTAGE: Logic 0; All inputs	V _{IL}	-0.3	0.8	V	22
INPUT LEAKAGE CURRENT: Any input 0V ≤ V _{IN} ≤ V _{DD} (All other pins not under test = 0V)	I _I	-5	5	μA	
OUTPUT LEAKAGE CURRENT: DQs are disabled; 0V ≤ V _{OUT} ≤ V _{DDQ}	I _{OZ}	-5	5	μA	
OUTPUT LEVELS: Output High Voltage (I _{OUT} = -4mA)	V _{OH}	2.4	–	V	
Output Low Voltage (I _{OUT} = 4mA)	V _{OL}	–	0.4	V	

WRITE – DQM OPERATION ¹



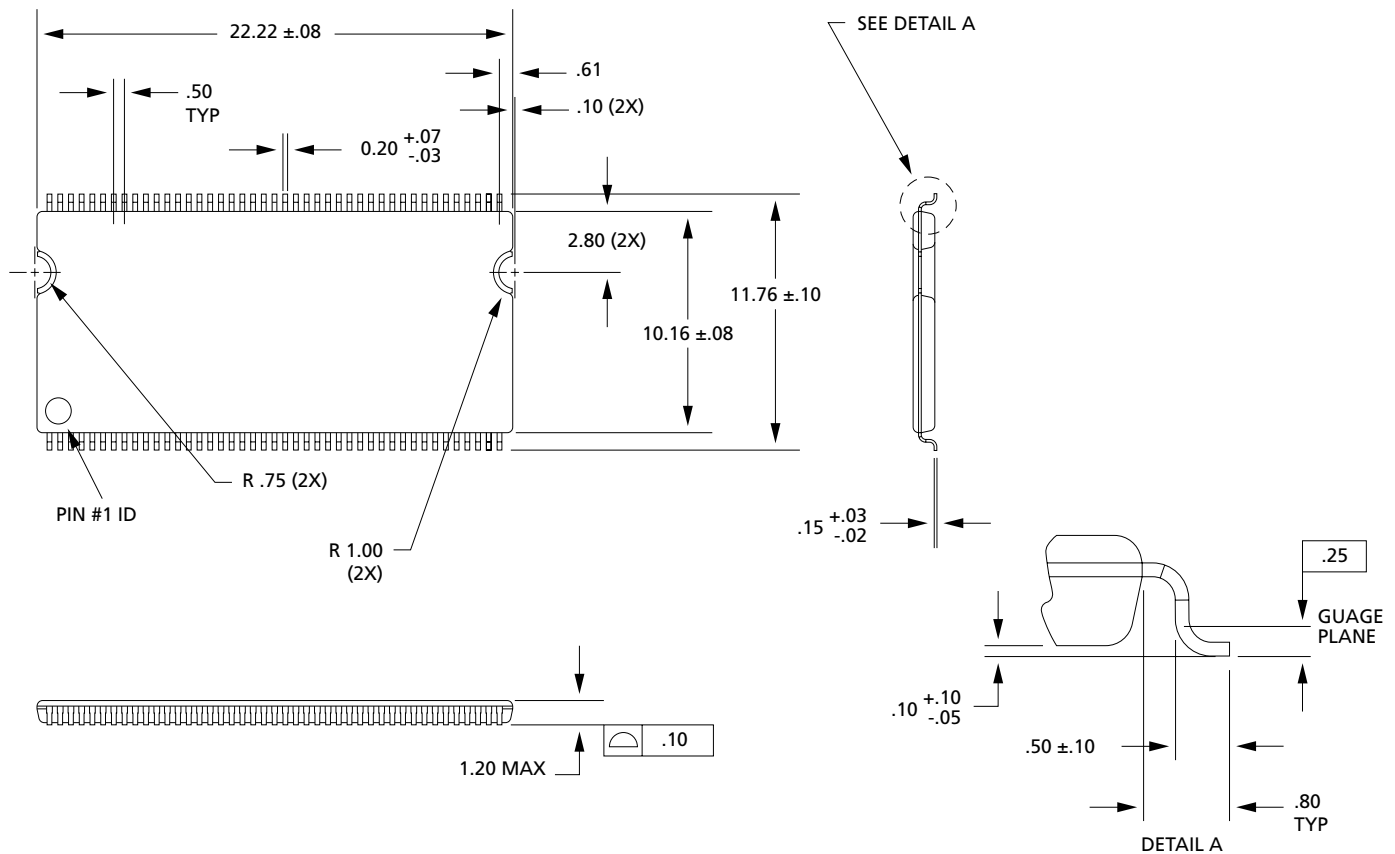
TIMING PARAMETERS

SYMBOL*	-5		-6		-7		UNITS
	MIN	MAX	MIN	MAX	MIN	MAX	
t _{AH}	1		1		1		ns
t _{AS}	1.5		1.5		2		ns
t _{CH}	2		2.5		2.75		ns
t _{CL}	2		2.5		2.75		ns
t _{CK} (3)	5		6		7		ns
t _{CK} (2)			10		10		ns
t _{CK} (1)			20		20		ns

SYMBOL*	-5		-6		-7		UNITS
	MIN	MAX	MIN	MAX	MIN	MAX	
t _{CKH}	1		1		1		ns
t _{CKS}	1.5		2		2		ns
t _{CMH}	1		1		1		ns
t _{CMS}	1.5		1.5		2		ns
t _{DH}	1		1		1		ns
t _{DS}	1.5		1.5		2		ns
t _{RCD}	15		18		20		ns

*CAS latency indicated in parentheses.

NOTE: 1. For this example, the burst length = 4.
2. A8 and A9 = "Don't Care."

86-PIN PLASTIC TSOP (400 MIL)


- NOTE:**
1. All dimensions in millimeters $\frac{\text{MAX}}{\text{MIN}}$ or typical where noted.
 2. Package width and length do not include mold protrusion; allowable mold protrusion is 0.025mm per side.



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